

**Tohlu Matsushima**

Okayama University

*For*

**Determination of Grounding Location for  
Guard Trace to Reduce Common-mode Radiation**

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**Qian Li**

Materials innovation institute, Delft University of  
Technology, NXP Semiconductor

*For*

**Hermeticity and Thermal Stability Testing of  
PECVD Silicon Nitride Thin-film Packages**

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**Chikara Ito**

Kyoto Institute of Technology

*For*

**Surface-mount Packaging of VCSEL onto Single-mode Waveguide  
for High-density Optical Interconnects Board**

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**Tsutomu Miyachi**

Yamaguchi University

*For*

**Development and Application of  
Large-scale Integrated Light-emitting Diodes**

**IEEE CPMT Young Award**

*Presented to*

**Yosuke Akagi**

Nihon University

*For*

**A Forming Method of Flat Fine Conductor on  
LTCC Green Sheet Using a Photo Resist Film**

*Presented at ICEP 2008*

*held on June 10-12, 2008 in Tokyo, Japan*

*Masahiro Aoyagi*

General Chairperson : Masahiro Aoyagi

IEEE CPMT (Components, Packaging, and  
Manufacturing Technology) Society Japan Chapter

*Hironori Asai*

General Chairperson : Hironori Asai

ICEP (International Conference on  
Electronics Packaging) 2008